

WHAT IS CLAIMED IS:

1. A component housing comprising:
a substrate;
a light pipe having a top and bottom surface is fitted through a bore in the substrate; and
a metallic surface finish coated on the cylindrical surface of the light pipe, wherein a solder joint is formed between the metallic finish and the bore in the substrate.
2. The component housing of claim 1 wherein light is transmitted through the bottom surface of the light pipe.
3. The component housing of claim 1, wherein the light pipe can be an array of light pipes.
4. The component housing of claim 1, wherein the substrate is a PCB.
5. The component housing of claim 1, wherein the light pipe is comprised of optically transparent material capable of transmitting optical signals.
6. The component housing of claim 1, wherein the solder joints the cylindrical portion of the light pipe coated with the metallic finish.
7. The component housing of claim 1, wherein the solder joint transmits both optical and electrical signals.
8. The component housing of claim 1, wherein the light pipe is mechanically attached to the substrate by the solder joint.

9. The component housing of claim 1, wherein the substrate enables transmission of two signals for each light pipe connection.
10. The component housing of claim 1, wherein the metallic finish is OSP.
11. The component housing of claim 1, wherein the metallic finish is HASL.